

Complementary Silicon Power Transistors

MJF3055 (NPN), MJF2955 (PNP)

Specifically designed for general purpose amplifier and switching applications.

Features

- Isolated Overmold Package (1500 Volts RMS Min)
- Electrically Similar to the Popular MJE3055T and MJE2955T
- Collector-Emitter Sustaining Voltage – $V_{CEO(sus)}$ 90 V
- 10 Amperes Rated Collector Current
- No Isolating Washers Required
- Reduced System Cost
- UL Recognized, File #E69369, to 3500 V_{RMS} Isolation
- Epoxy Meets UL 94 V-0 at 0.125 in
- ESD Ratings: Machine Model, C; > 400 V
Human Body Model, 3B; > 8000 V
- Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Sustaining Voltage	$V_{CEO(sus)}$	90	Vdc
Collector-Emitter Breakdown Voltage	V_{CES}	90	Vdc
Base-Emitter Voltage	V_{EBO}	5.0	Vdc
Collector Current – Continuous	I_C	10	Adc
Base Current – Continuous	I_B	6.0	Adc
RMS Isolation Voltage (Note 3) ($t = 0.3$ sec, R.H. $\leq 30\%$, $T_A = 25^\circ\text{C}$) Per Figure 5	V_{ISOL}	4500	V_{RMS}
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ (Note 2) Derate above 25°C	P_D	30 0.25	W W/ $^\circ\text{C}$
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	2.0 0.016	W W/ $^\circ\text{C}$
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case (Note 2)	$R_{\theta JC}$	4.0	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Lead Temperature for Soldering Purposes	T_L	260	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

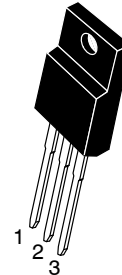
1. Pulse Test: Pulse Width = 5.0 ms, Duty Cycle $\leq 10\%$.
2. Measurement made with thermocouple contacting the bottom insulated surface (in a location beneath the die), the devices mounted on a heatsink with thermal grease and a mounting torque of ≥ 6 in. lbs.
3. Proper strike and creepage distance must be provided.

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

COMPLEMENTARY SILICON POWER TRANSISTORS

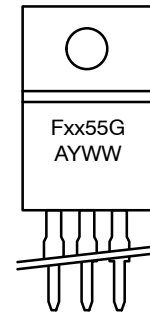
10 AMPERES

90 VOLTS, 30 WATTS



TO-220 FULLPACK
CASE 221D
STYLE 2

MARKING DIAGRAM



Fxx55 = Specific Device Code
xx = 29 or 30
G = Pb-Free Package
A = Assembly Location
Y = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MJF2955	TO-220 FULLPACK	50 Units/Rail
MJF2955G	TO-220 FULLPACK (Pb-Free)	50 Units/Rail
MJF3055	TO-220 FULLPACK	50 Units/Rail
MJF3055G	TO-220 FULLPACK (Pb-Free)	50 Units/Rail

MJF3055 (NPN), MJF2955 (PNP)

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS (Note 4)				
Collector-Emitter Sustaining Voltage ($I_C = 200\text{ mAdc}$, $I_B = 0$)	$V_{CE(sus)}$	90	–	Vdc
Collector Cutoff Current ($V_{CE} = 90\text{ Vdc}$, $V_{BE} = 0$)	I_{CES}	–	1.0	$\mu\text{A dc}$
Collector Cutoff Current ($V_{CE} = 90\text{ Vdc}$, $I_E = 0$)	I_{CBO}	–	1.0	$\mu\text{A dc}$
Emitter-Base Leakage ($V_{EB} = 5.0\text{ Vdc}$, $I_C = 0$)	I_{EBO}	–	1.0	$\mu\text{A dc}$
ON CHARACTERISTICS (Note 4)				
DC Current Gain ($I_{CE} = 4.0\text{ Adc}$, $V_{CE} = 4.0\text{ Vdc}$) ($I_{CE} = 10\text{ Adc}$, $V_{CE} = 4.0\text{ Vdc}$)	h_{FE}	20 5.0	100 –	–
Collector-Emitter Saturation Voltage ($I_C = 4.0\text{ Adc}$, $I_B = 0.4\text{ Adc}$) ($I_C = 10\text{ Adc}$, $I_B = 3.3\text{ Adc}$)	$V_{CE(sat)}$	– –	1.0 2.5	Vdc
Base-Emitter On Voltage ($I_C = 4.0\text{ Adc}$, $V_{BE} = 4.0\text{ Vdc}$)	$V_{BE(on)}$	–	1.5	Vdc
DYNAMIC CHARACTERISTICS				
Current-Gain-Bandwidth Product ($V_{CE} = 10\text{ Vdc}$, $I_C = 0.5\text{ Adc}$, $f_{test} = 500\text{ kHz}$)	f_T	2.0	–	MHz

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: Pulse Width = 5.0 ms, Duty Cycle \leq 10%.

MJF3055 (NPN), MJF2955 (PNP)

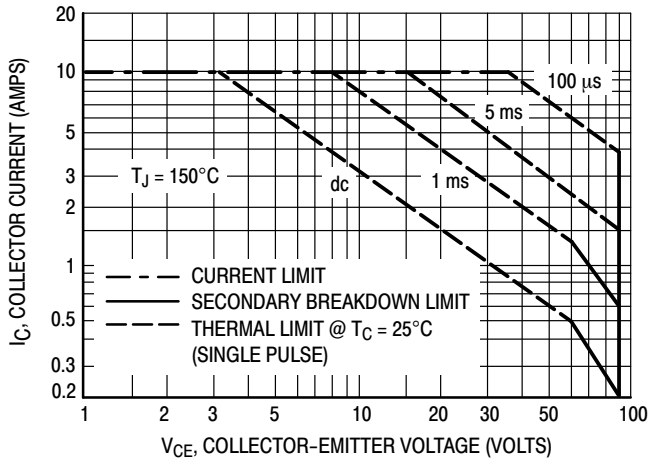


Figure 1. Maximum Forward Bias Safe Operating Area

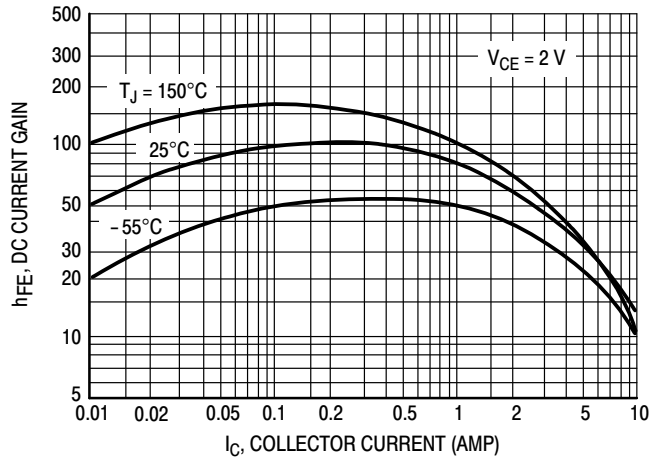


Figure 2. DC Current Gain

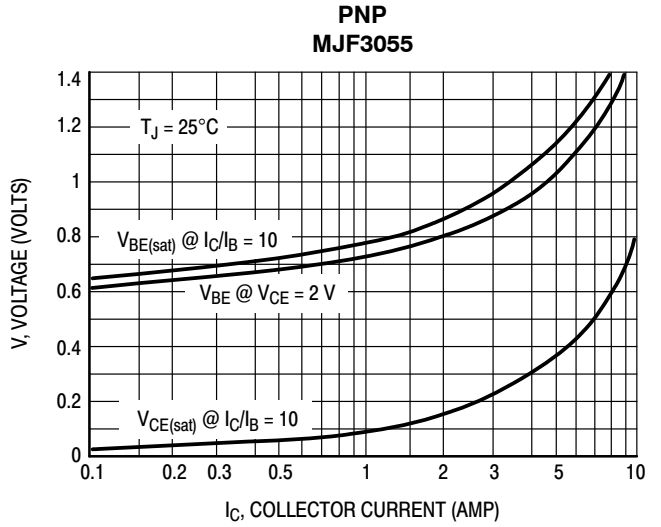
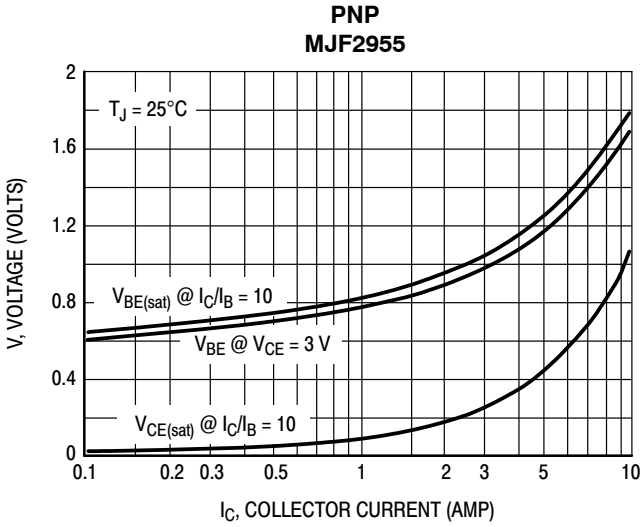


Figure 3. "On" Voltages

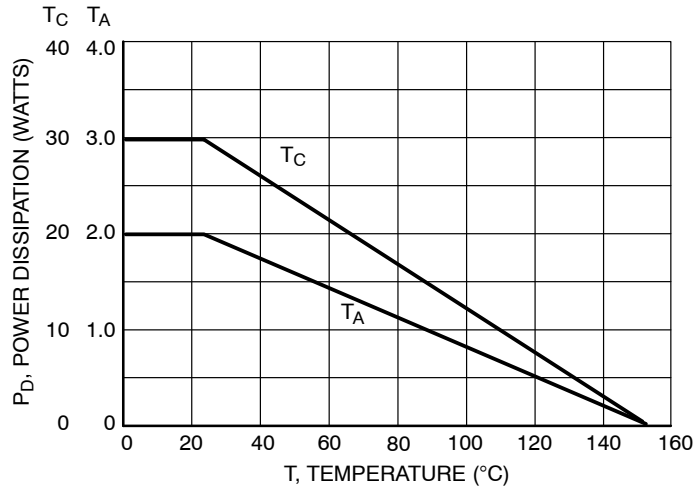


Figure 4. Power Derating

MJF3055 (NPN), MJF2955 (PNP)

TEST CONDITIONS FOR ISOLATION TESTS*

FULLY ISOLATED PACKAGE

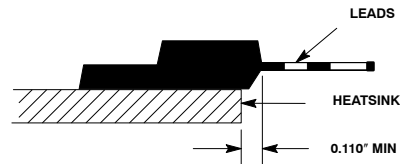


Figure 5. Mounting Position

*Measurement made between leads and heatsink with all leads shorted together.

MOUNTING INFORMATION

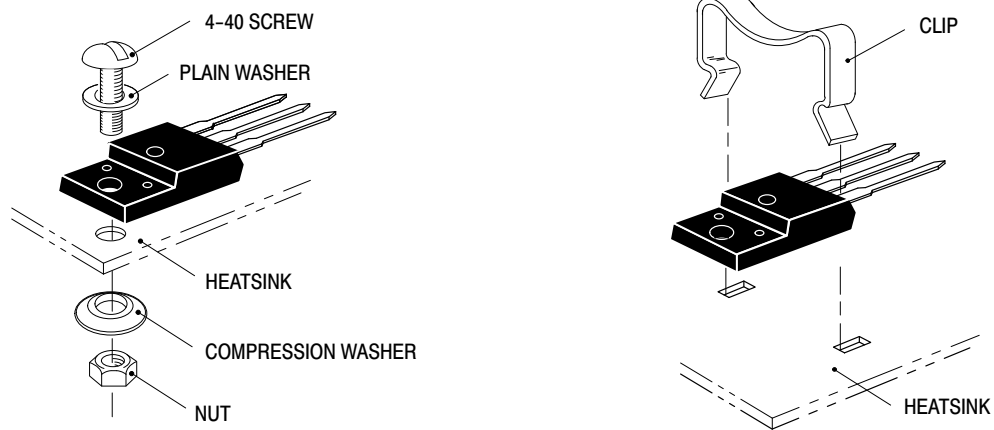


Figure 6. Typical Mounting Techniques*

Laboratory tests on a limited number of samples indicate, when using the screw and compression washer mounting technique, a screw torque of 6 to 8 in · lbs is sufficient to provide maximum power dissipation capability. The compression washer helps to maintain a constant pressure on the package over time and during large temperature excursions.

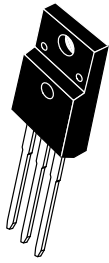
Destructive laboratory tests show that using a hex head 4-40 screw, without washers, and applying a torque in excess of 20 in · lbs will cause the plastic to crack around the mounting hole, resulting in a loss of isolation capability.

Additional tests on slotted 4-40 screws indicate that the screw slot fails between 15 to 20 in · lbs without adversely affecting the package. However, in order to positively ensure the package integrity of the fully isolated device, **onsemi** does not recommend exceeding 10 in · lbs of mounting torque under any mounting conditions.

**For more information about mounting power semiconductors see Application Note AN1040.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

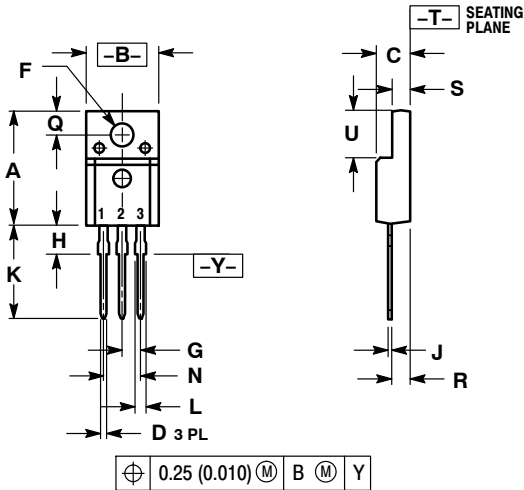
ON Semiconductor®



SCALE 1:1

TO-220 FULLPAK CASE 221D-03 ISSUE K

DATE 27 FEB 2009



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH
 3. 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

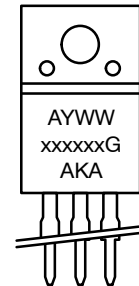
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.617	0.635	15.67	16.12
B	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
H	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

MARKING DIAGRAMS

- | | | |
|--|---|--|
| STYLE 1:
PIN 1. GATE
2. DRAIN
3. SOURCE | STYLE 2:
PIN 1. BASE
2. COLLECTOR
3. EMITTER | STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE |
| STYLE 4:
PIN 1. CATHODE
2. ANODE
3. CATHODE | STYLE 5:
PIN 1. CATHODE
2. ANODE
3. GATE | STYLE 6:
PIN 1. MT 1
2. MT 2
3. GATE |



Bipolar



Rectifier

- | | |
|-------------------------------|---------------------------|
| xxxxxx = Specific Device Code | A = Assembly Location |
| G = Pb-Free Package | Y = Year |
| A = Assembly Location | WW = Work Week |
| Y = Year | xxxxxx = Device Code |
| WW = Work Week | G = Pb-Free Package |
| | AKA = Polarity Designator |

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